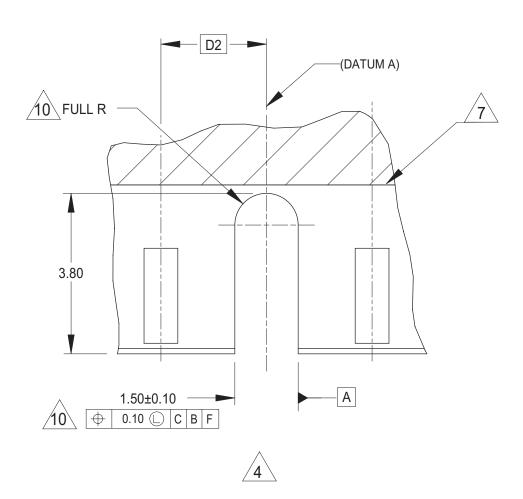


### **CENTER KEY CONFIGURATION**



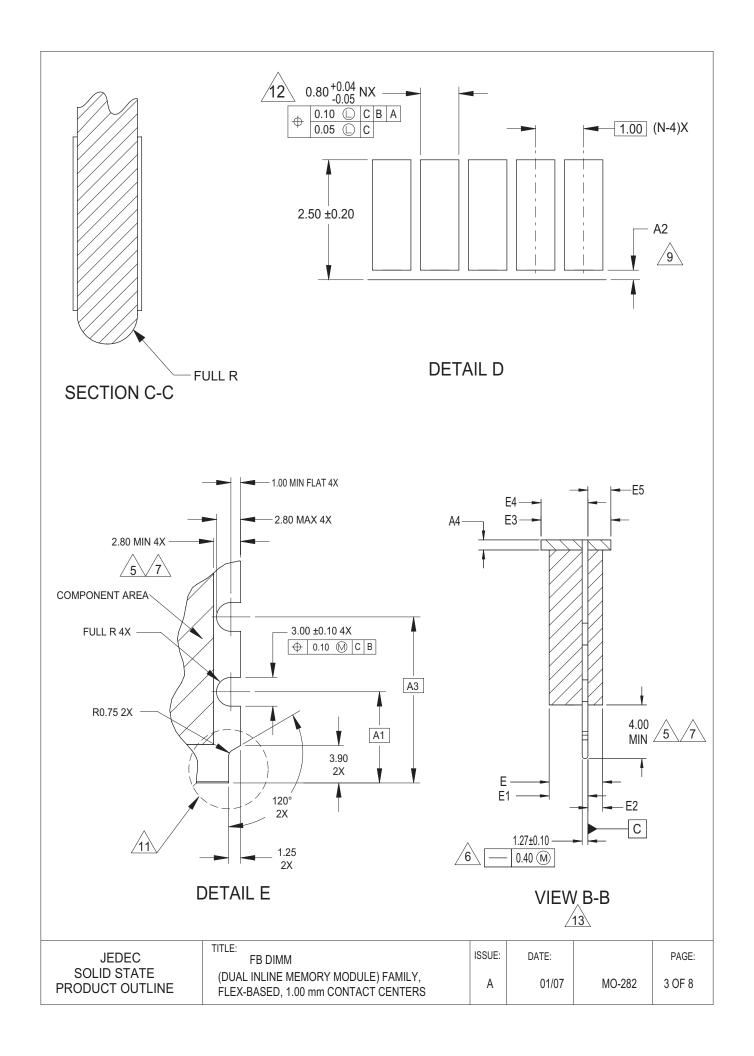
JEDEC SOLID STATE PRODUCT OUTLINE THIS REGISTERED OUTLINE HAS BEEN PREPARED AND PUBLISHED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USE IN THE ELECTRONICS INDUSTRY. CHANGES ARE LIKELY TO OCCUR.

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**DETAIL A: CENTER KEY ZONE** 

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## COMMON DIMENSION TABLE

SYMBOL	MIN	NOM	MAX	NOTES
A1		9.50 BASIC		
A2	0.35	0.55	.75	
A3		17.30 BASIC		
D	133.20	133.35	133.50	
e1		67.00 BASIC		
e2		51.00 BASIC		
N		240		8
				·
NOTES	1, 2, 3			
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## **VARIATIONS**

VAR		AA			AB		AC		NOTES	
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	NOTES
А	30.20	30.35	30.50	30.20	30.35	30.50	30.20	30.35	30.50	
A4	0.40			0.40			0.40			
D1	8	.00 BASIC		8	.00 BASIC		3	3.00 BASIC		4
D2	2	.50 BASIC		2	.50 BASIC		2	2.50 BASIC		4
Е			6.20			7.20			5.00	
E1			3.60			4.20			3.80	
E2			2.60			3.00			1.20	
E3			6.75			6.75			5.00	
E4			3.75			3.75			3.80	
E5			3.00			3.00			1.20	
NOTES	1, 2, 3									
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ISSUE	Α									

VAR		AD								NOTEC
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	NOTES
Α	30.20	30.35	30.50							
A4	0.40									
D1	8	.00 BASIC								4
D2	2	.50 BASIC								4
E			5.60							
E1			3.80							
E2			1.80							
E3			5.00							
E4			3.80							
E5			1.20							
							•			
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## **VARIATIONS**

VAR		ВА			ВВ					NOTES
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	NOTES
Α	37.85	38.00	38.15	37.85	38.00	38.15				
A4	7.75			7.75						
D1	8	.00 BASIC			8.00 BASI	0				4
D2	2	.50 BASIC			2.50 BASI	С				4
E			6.20			7.20				
E1			3.60			4.20				
E2			2.60			3.00				
E3			6.75			6.75				
E4			3.75			3.75				
E5			3.00			3.00				
NOTES	1, 2, 3									
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#### NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE NOTED.
- 3. ALL DIMENSIONS ARE IN MILLIMETERS (mm).
- THE JC-45.4 COMMITTEE CONTROLS THE SIGNIFICANCE OF OFFSET KEY POSITION. IT IS SHOWN FOR REFERENCE ONLY, AND IS SUBJECT TO CHANGE.
- DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON ONE OR BOTH SIDES.
- 6 CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION. STRAIGHTNESS CALLOUT APPLIES TO ZONE DEFINED BY THE 4.00 CONTACT AREA DIMENSION FOR THE ENTIRE LENGTH OF 133.35.
- BORDER OF COMPONENT AREA. COMPONENT AREA INCLUDES ANY FLEX CIRCUIT MATERIAL PROJECTING BEYOND 1.37 MAX THICKNESS.
- N IS THE TOTAL NUMBER OF CIRCUIT CONTACTS (PINS, LEADS, TABS, PADS).

LEADING EDGE OF CONTACT PADS SHALL BE FREE OF EXTERNAL TRACES.

- OFFSET KEY FEATURES SHALL BE DEFINED BY NON-FLEX CIRCUIT MATERIAL. NO FLEX CIRCUIT MATERIAL SHALL BE ALLOWED TO PROTRUDE INTO OFFSET KEY.
- BOTH END NOTCHES MUST BE USED FOR MODULE KEYING.

#### **APPLICATION NOTES:**

- 12 RECOMMENDED PLATING FOR CONTACT PADS ARE:
  - 1) PREFERABLE PLATING: ELECTROLYTIC GOLD PLATING 0.76 MICROMETERS MINIMUM OVER ELECTROLYTIC NICKEL 2.00 MICROMETERS MINIMUM.
  - 2) ALTERNATIVE PLATING: GOLD PLATING 0.05-0.75 MICROMETERS OVER NICKEL 2.00 MICROMETERS MINIMUM MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
- VIEW B-B MODULE THICKNESS INCLUDES EXTERNAL HEAT SPREADER FOR VARIATIONS AB, AD AND BB.

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# TO CONFIGURATIONS OF THIS OUTLINE. THESE APPLICATIONS INCLUDE:

10/934,027

11/005,992

11/007,551

11/068,688

11/077,952

11/123,721

11/157,565

11/193,954

11/321,418

11/331,969

STAKTEK INTENDS TO COMPLY WITH THE JEDEC PATENT POLICY.

JEDEC
SOLID STATE
PRODUCT OUTLINE

TITLE: FB DIMM
(DUAL INLINE MEMORY MODULE) FAMILY,
FLEX-BASED, 1.00 mm CONTACT CENTERS

#### **Change Record**

If the change involves any words added or deleted (excluding deletion of accidentally repeated words), the change is to be included below. Punctuation changes may or may not be included.

Initial Issue: A	Date: 01/0	7 JC11 Item	Number: 11.14-099
		•	

Change Record History							
Issue:	Date:	Item Number:					
Description of Changes							

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